

. reescale Semiconductor

Technical Data

Replaced by MHPA19010N. There are no form, fit or function changes with this part replacement. N suffix added to part number to indicate transition to lead-free terminations.

PCS Band RF Linear LDMOS Amplifier

Designed for Class AB amplifier applications in 50 ohm systems operating in the PCS frequency band. A silicon FET design provides outstanding linearity and gain. In addition, the excellent group delay and phase linearity characteristics are ideal for digital modulation systems, such as TDMA and CDMA.

- Typical CDMA Performance: 1960 MHz, 28 Volts IS-95 CDMA Pilot, Sync, Paging, Traffic Codes 8 Through 13
- Adjacent Channel Power: -51 dBc @ 30 dBm, 885 kHz Channel Spacing
- Power Gain: 24.5 dB Min (@ f = 1960 MHz)
- Excellent Phase Linearity and Group Delay Characteristics
- 0.2 dB Typical Gain Flatness
- Ideal for Feedforward Base Station Applications

MHPA19010

1930-1990 MHz 10 W, 24.5 dB RF HIGH POWER LDMOS AMPLIFIER

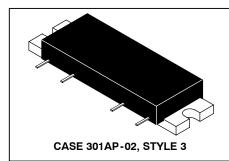


Table 1. Maximum Ratings (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
DC Supply Voltage	V_{DD}	30	Vdc
RF Input Power (Single Carrier CW)	P _{in}	+20	dBm
Storage Temperature Range	T _{stg}	- 40 to +100	°C
Operating Case Temperature Range	T _C	- 20 to +100	°C
Quiescent Bias Current	I _{DQ}	750	mA

Table 2. Electrical Characteristics (V_{DD} = 28 Vdc, $V_{BIAS} \cong 8$ V Set for Supply Current of 600 mA, T_C = 25°C, 50 Ω System)

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Characteristi	С	Symbol	Min	Тур	Max	Unit
Supply Current		I _{DD}	_	600	_	mA
Power Gain	(f = 1960 MHz)	G _p	24.5	25	_	dB
Gain Flatness	(f = 1930 - 1990 MHz)	G _F	_	0.2	0.5	dB
Power Output @ 1 dB Comp.	(f = 1960 MHz)	P1dB	_	41.5	_	dBm
Input VSWR	(f = 1930 - 1990 MHz)	VSWR _{in}	_	1.5:1	2:1	
Noise Figure	(f = 1960 MHz)	NF	_	8	10	dB
Adjacent Channel Power Rejection @ 30 d 885 kHz Channel Spacing	Bm, 1.23 MHz BW,	ACPR	_	-58	- 51	dBc



TYPICAL CHARACTERISTICS

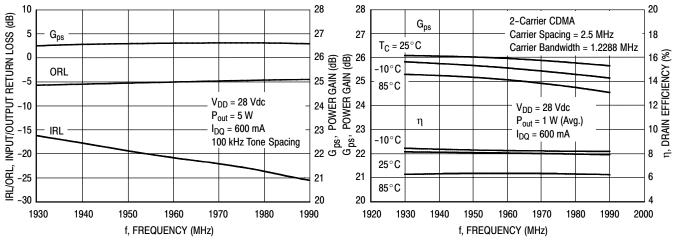


Figure 1. Two-Tone Power Gain, Input Return Loss and Output Return Loss versus Frequency

Figure 2. 2-Carrier CDMA Power Gain and Efficiency versus Frequency

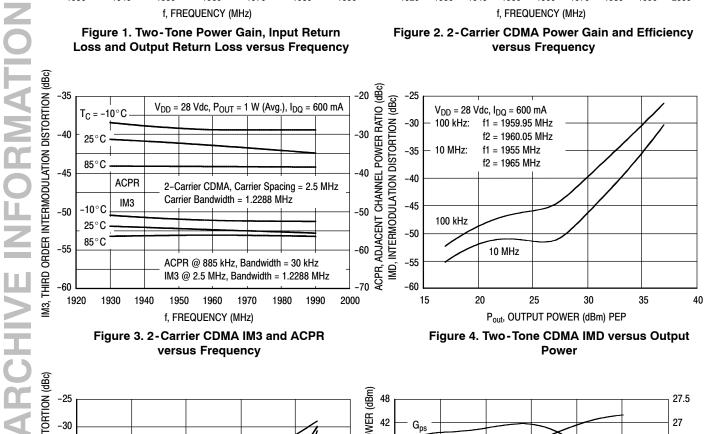


Figure 3. 2-Carrier CDMA IM3 and ACPR versus Frequency

Figure 4. Two-Tone CDMA IMD versus Output **Power**

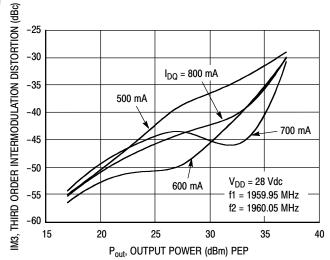


Figure 5. Third Order Intermodulation Distortion versus Output Power

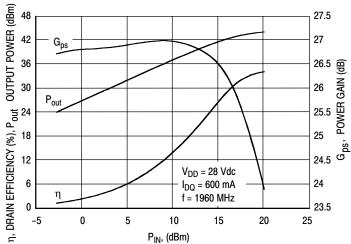


Figure 6. CW Output Power, Efficiency and Gain versus Input Power



ARCHIVE INFORMATION

TYPICAL CHARACTERISTICS

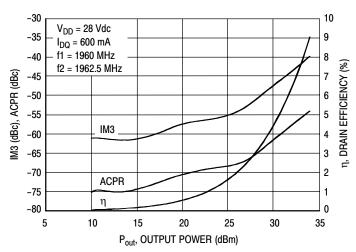


Figure 7. 2-Carrier CDMA ACPR, IM3 and Efficiency versus Output Power



NOTES





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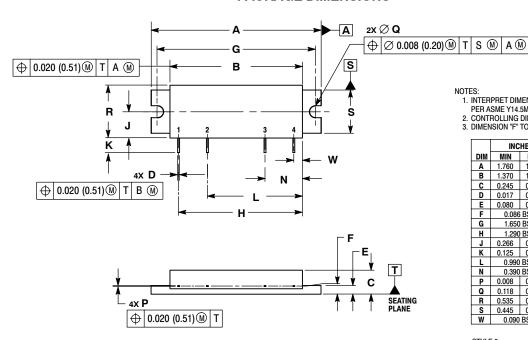


NOTES



ARCHIVE INFORMATION

PACKAGE DIMENSIONS



NOTES:

- I. INTERPRET DIMENSIONS AND TOLERANCES
 PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION "F" TO CENTER OF LEADS.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	1.760	1.780	44.70	45.21	
В	1.370	1.390	34.80	35.31	
С	0.245	0.265	6.22	6.73	
D	0.017	0.023	0.43	0.58	
E	0.080	0.100	2.03	2.54	
F	0.086	BSC	2.18 BSC		
G	1.650	BSC	41.91 BSC		
Н	1.290	BSC	32.77	BSC	
J	0.266	0.280	6.76	7.11	
K	0.125	0.165	3.18	4.19	
L	0.990	BSC	25.15 BSC		
N	0.390	BSC	9.91 BSC		
Р	0.008	0.013	0.20	0.33	
Q	0.118	0.132	3.00	3.35	
R	0.535	0.555	13.59	14.10	
S	0.445	0.465	11.30	11.81	
W	0.090	BSC	2.29 BSC		

STYLE 3:
PIN 1. RF INPUT
2. VBIAS
3. VDD
4. RF OUTPUT
CASE: GROUND

CASE 301AP-02 ISSUE C

Note: V_{DD} (Pin 3) should always be applied before V_{BIAS} (Pin 2).

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